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E. Willio
8-20-02



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

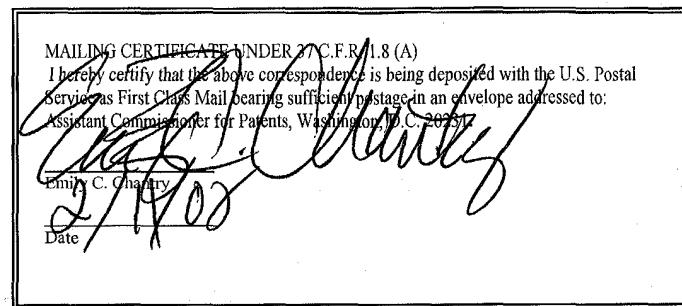
Applicant: Morrison, et al.
Serial No.: 10/034827
Filed: 01/03/2002
Docket: TI-31373
For:

**CHIP-SCALE PACKAGES STACKED ON FOLDED
INTERCONNECTOR FOR VERTICAL ASSEMBLY ON SUBSTRATES.**

REQUEST FOR CORRECTED FILING DATE

February 11, 2002

Assistant Commissioner
for Patents
Washington, D.C. 20231



Sir:

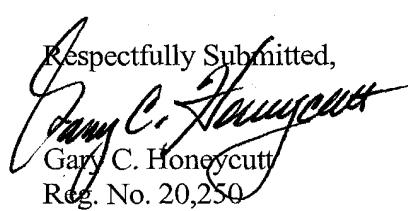
Applicant received a postcard indicating a filing date of January 3, 2002 for the above referenced Application.

However, the Mailing Certificate confirms that the Application was deposited with the U.S. Postal Service Express Mail (Label No. EV051432549US) on December 26, 2001.

A Declaration by Emily Chantry is enclosed to further corroborate mailing by Express Mail on December 26, 2001.

Applicant requests that the official filing date be corrected to **December 26, 2001** to reflect the date of mailing.

Respectfully Submitted,


Gary C. Honeycutt

Reg. No. 20,250

Attorney for Applicant

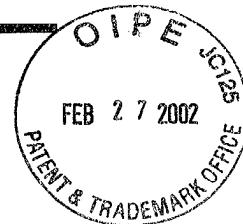
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G O D W I N

R U B E R

0410

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February 11, 2002

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VIA FIRST CLASS MAIL

Assistant Commissioner for Patents
Washington, D.C. 20231

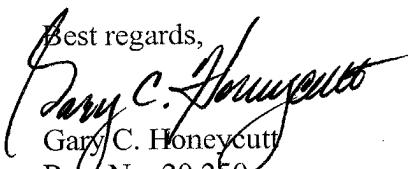
Re: Patent Application For
CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR
FOR VERTICAL ASSEMBLY ON SUBSTRATES
Owner: Texas Instruments Incorporated
Serial No.: 10/034827
Attorney Docket No. TI-31373
Our File: 50000.2166

Dear Sir:

Enclosed for filing please find the following items relating to the above-identified application:

- (1) Request for Corrected Filing Date; and
- (2) Postcards.

Please file the application and return the date-stamped postcard to the corresponding addresses as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Best regards,

Gary C. Honeycutt
Reg. No. 20,250

GCH/ecc
Encls.
cc: Larry Bassuk, Texas Instruments Incorporated



TI-31373

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Morrison, et al.
Serial No.: 10/034827
Filed: 01/03/2002
Docket: TI-31373
For: **CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR
FOR VERTICAL ASSEMBLY ON SUBSTRATES.**

DECLARATION

Emily Chantry of Plano, Texas hereby declares that she is a secretary at Godwin Gruber, P.C., and that she has more than 3 years experience in the preparation and mailing of papers to the United States Patent and Trademark Office (USPTO);

THAT in the performance of her duties as secretary of Gary C. Honeycutt, attorney of record, she prepared and mailed Application Serial Number 10/034,827 on December 26, 2001;

THAT said Application was placed in an Express Mail envelope, bearing proper postage, and then deposited with the U.S. Postal Service Express Mail Service, labeled with Mailing Label No. EV051432549US, on December 26, 2001; and

THAT Exhibit A, attached, is a true copy of the original Transmittal Form for said Application Serial Number 10/034,827 (Attorney Docket No. 31373) showing a duly executed Express Mailing Certificate, dated December 26, 2001, confirming that the Application is entitled to an Official Filing Date of December 26, 2001.

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Signed:

Emily C. Chantry

Date:

2/11/02